



# PSMN1R5-30BLE

N-channel 30 V 1.5 mΩ logic level MOSFET in D2PAK

12 October 2012

Product data sheet

## 1. Product profile

### 1.1 General description

Logic level N-channel MOSFET in D2PAK package qualified to 175 °C. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

### 1.2 Features and benefits

- Enhanced forward biased safe operating area for superior linear mode operation
- Very low  $R_{DS(on)}$  for low conduction losses

### 1.3 Applications

- Electronic fuse
- Hot swap
- Load switch
- Soft start

### 1.4 Quick reference data

Table 1. Quick reference data

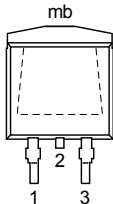
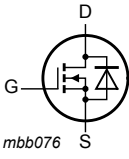
| Symbol                  | Parameter                        | Conditions  |     | Min | Typ  | Max  | Unit |
|-------------------------|----------------------------------|---|-----|-----|------|------|------|
| V <sub>DS</sub>         | drain-source voltage             | T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 175 °C   |     | -   | -    | 30   | V    |
| I <sub>D</sub>          | drain current                    | T <sub>mb</sub> = 25 °C; V <sub>GS</sub> = 10 V; <a href="#">Fig. 1</a>   | [1] | -   | -    | 120  | A    |
| P <sub>tot</sub>        | total power dissipation          | T <sub>mb</sub> = 25 °C; <a href="#">Fig. 2</a>   |     | -   | -    | 401  | W    |
| Static characteristics  |                                  |   |     |     |      |      |      |
| R <sub>DSon</sub>       | drain-source on-state resistance | V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 12</a>                            |     | -   | 1.3  | 1.5  | mΩ   |
|                         |                                  | V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 12</a>                           |     | -   | 1.7  | 1.85 | mΩ   |
| Dynamic characteristics |                                  |   |     |     |      |      |      |
| Q <sub>GD</sub>         | gate-drain charge                | V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 25 A; V <sub>DS</sub> = 15 V; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a> |     | -   | 33.2 | -    | nC   |
| Q <sub>G(tot)</sub>     | total gate charge                | V <sub>GS</sub> = 10 V; I <sub>D</sub> = 25 A; V <sub>DS</sub> = 15 V; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>  |     | -   | 228  | -    | nC   |

| Symbol                      | Parameter                                    | Conditions   | Min | Typ | Max  | Unit |
|-----------------------------|--|--|-----|-----|------|------|
| <b>Avalanche ruggedness</b> |  |  |     |     |      |      |
| $E_{DS(AL)S}$               | non-repetitive drain-source avalanche energy | $V_{GS} = 10\text{ V}$ ; $T_{j(\text{init})} = 25\text{ °C}$ ; $I_D = 120\text{ A}$ ; $V_{sup} \leq 30\text{ V}$ ; unclamped; $R_{GS} = 50\text{ }\Omega$ ; <a href="#">Fig. 3</a> | -   | -   | 1990 | mJ   |

[1] Capped at 120A due to package

## 2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description                       | Simplified outline   | Graphic symbol  |
|-----|--------|-----------------------------------|--|---|
| 1   | G      | gate                              |  <p><b>D2PAK (SOT404)</b></p> |  |
| 2   | D      | drain[1]                          |  |   |
| 3   | S      | source                            |  |   |
| mb  | D      | mounting base; connected to drain |  |   |

[1] It is not possible to make connection to pin 2.

## 3. Ordering information

Table 3. Ordering information

| Type number   | Package |  |         |
|---------------|---------|--|---------|
|               | Name    | Description  | Version |
| PSMN1R5-30BLE | D2PAK   | plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) | SOT404  |

## 4. Marking

Table 4. Marking codes

| Type number   | Marking code  |
|---------------|---------------|
| PSMN1R5-30BLE | PSMN1R5-30BLE |

## 5. Limiting values

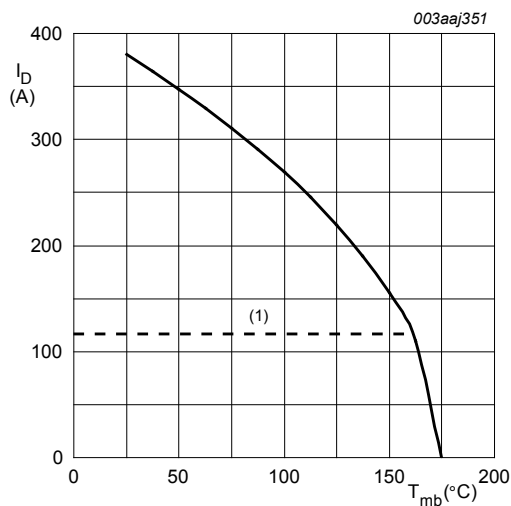
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol    | Parameter            | Conditions  | Min | Max | Unit |
|-----------|----------------------|---|-----|-----|------|
| $V_{DS}$  | drain-source voltage | $T_j \geq 25\text{ °C}$ ; $T_j \leq 175\text{ °C}$                                | -   | 30  | V    |
| $V_{DGR}$ | drain-gate voltage   | $T_j \leq 175\text{ °C}$ ; $T_j \geq 25\text{ °C}$ ; $R_{GS} = 20\text{ k}\Omega$ | -   | 30  | V    |

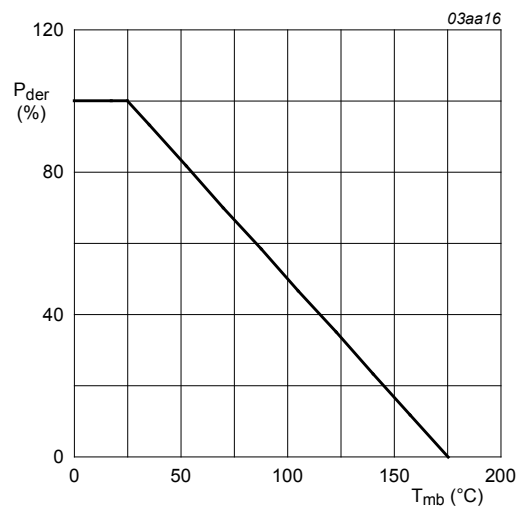
| Symbol                      | Parameter                                    | Conditions  |     | Min | Max  | Unit               |
|-----------------------------|--|---|-----|-----|------|--------------------|
| $V_{GS}$                    | gate-source voltage                          |   |     | -20 | 20   | V                  |
| $I_D$                       | drain current                                | $V_{GS} = 10\text{ V}; T_{mb} = 100\text{ }^{\circ}\text{C}; \text{Fig. 1}$   | [1] | -   | 120  | A                  |
|                             |  | $V_{GS} = 10\text{ V}; T_{mb} = 25\text{ }^{\circ}\text{C}; \text{Fig. 1}$  | [1] | -   | 120  | A                  |
| $I_{DM}$                    | peak drain current                           | pulsed; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ }^{\circ}\text{C}; \text{Fig. 4}$  |     | -   | 1521 | A                  |
| $P_{tot}$                   | total power dissipation                      | $T_{mb} = 25\text{ }^{\circ}\text{C}; \text{Fig. 2}$  |     | -   | 401  | W                  |
| $T_{stg}$                   | storage temperature                          |   |     | -55 | 175  | $^{\circ}\text{C}$ |
| $T_j$                       | junction temperature                         |   |     | -55 | 175  | $^{\circ}\text{C}$ |
| $T_{sld(M)}$                | peak soldering temperature                   |   |     | -   | 260  | $^{\circ}\text{C}$ |
| <b>Source-drain diode</b>   |  |   |     |     |      |                    |
| $I_S$                       | source current                               | $T_{mb} = 25\text{ }^{\circ}\text{C}$   | [1] | -   | 120  | A                  |
| $I_{SM}$                    | peak source current                          | pulsed; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ }^{\circ}\text{C}$   |     | -   | 1521 | A                  |
| <b>Avalanche ruggedness</b> |  |   |     |     |      |                    |
| $E_{DS(AL)S}$               | non-repetitive drain-source avalanche energy | $V_{GS} = 10\text{ V}; T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}; I_D = 120\text{ A}; V_{sup} \leq 30\text{ V}; \text{unclamped}; R_{GS} = 50\text{ }\Omega; \text{Fig. 3}$ |     | -   | 1990 | mJ                 |

[1] Capped at 120A due to package



**Fig. 1. Continuous drain current as a function of mounting base temperature**

$$V_{GS} \geq 10\text{ V}$$



**Fig. 2. Normalized total power dissipation as a function of mounting base temperature**

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100\%$$

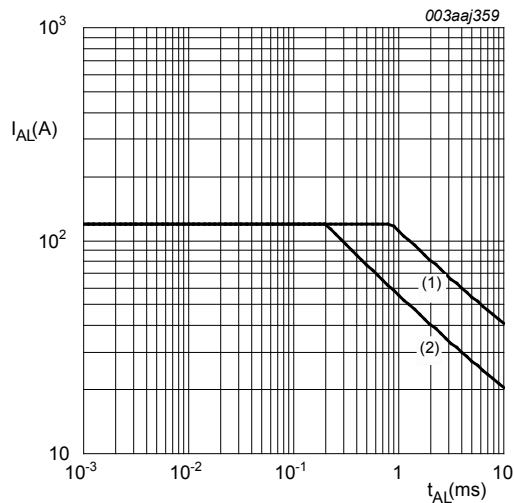


Fig. 3. Single pulse avalanche rating; avalanche current as a function of avalanche time

(1)  $T_{j (int)} = 25^{\circ}C$ ; (2)  $T_{j (int)} = 100^{\circ}C$

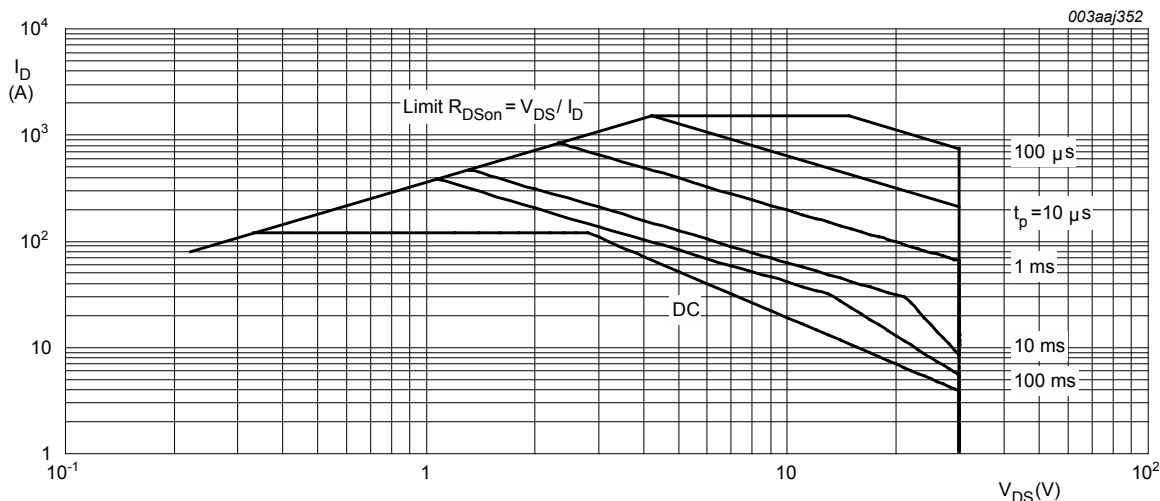


Fig. 4. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$T_{mb} = 25^{\circ}C$ ;  $I_{DM}$  is a single pulse

6. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter   | Conditions                   | Min | Typ | Max  | Unit |
|----------------|---|------------------------------|-----|-----|------|------|
| $R_{th(j-mb)}$ | thermal resistance from junction to mounting base | Fig. 5                       | -   | 0.3 | 0.37 | K/W  |
| $R_{th(j-a)}$  | thermal resistance from junction to ambient       | minimum footprint; FR4 board | -   | 50  | -    | K/W  |

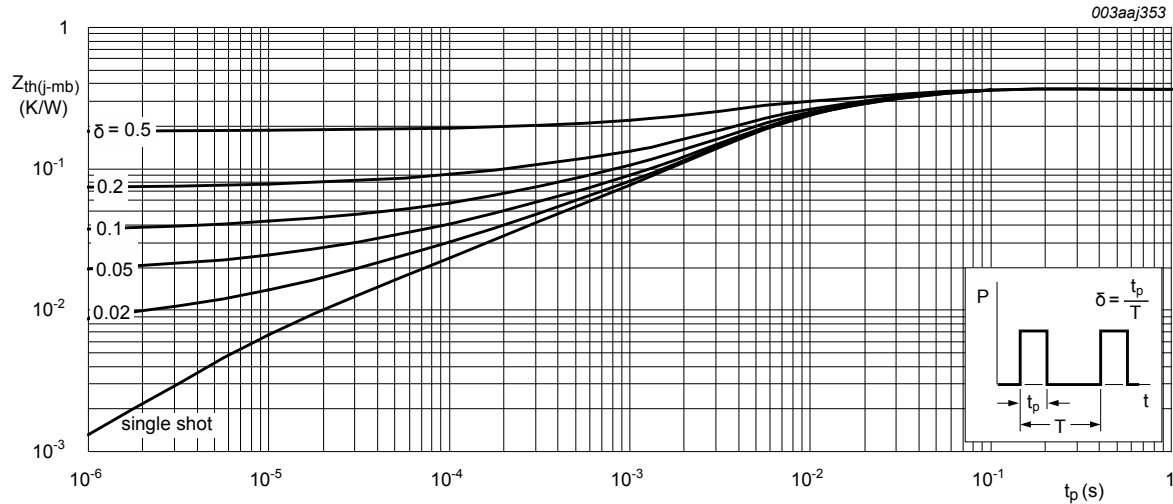


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

## 7. Characteristics

Table 7. Characteristics

| Symbol                        | Parameter                        | Conditions   | Min | Typ | Max  | Unit    |
|-------------------------------|----------------------------------|--|-----|-----|------|---------|
| <b>Static characteristics</b> |                                  |  |     |     |      |         |
| $V_{(BR)DSS}$                 | drain-source breakdown voltage   | $I_D = 250 \mu A$ ; $V_{GS} = 0 V$ ; $T_J = -55 ^\circ C$  | 27  | -   | -    | V       |
|                               |                                  | $I_D = 250 \mu A$ ; $V_{GS} = 0 V$ ; $T_J = 25 ^\circ C$   | 30  | -   | -    | V       |
| $V_{GS(th)}$                  | gate-source threshold voltage    | $I_D = 1 mA$ ; $V_{DS} = V_{GS}$ ; $T_J = 175 ^\circ C$ ; <a href="#">Fig. 10</a>                          | 0.5 | -   | -    | V       |
|                               |                                  | $I_D = 1 mA$ ; $V_{DS} = V_{GS}$ ; $T_J = 25 ^\circ C$ ; <a href="#">Fig. 11</a> ; <a href="#">Fig. 10</a> | 1.3 | 1.7 | 2.15 | V       |
|                               |                                  | $I_D = 1 mA$ ; $V_{DS} = V_{GS}$ ; $T_J = -55 ^\circ C$ ; <a href="#">Fig. 10</a>                          | -   | -   | 2.45 | V       |
| $I_{DSS}$                     | drain leakage current            | $V_{DS} = 30 V$ ; $V_{GS} = 0 V$ ; $T_J = 25 ^\circ C$   | -   | 0.5 | 10   | $\mu A$ |
|                               |                                  | $V_{DS} = 30 V$ ; $V_{GS} = 0 V$ ; $T_J = 100 ^\circ C$  | -   | -   | 200  | $\mu A$ |
| $I_{GSS}$                     | gate leakage current             | $V_{GS} = 16 V$ ; $V_{DS} = 0 V$ ; $T_J = 25 ^\circ C$   | -   | 10  | 100  | nA      |
|                               |                                  | $V_{GS} = -16 V$ ; $V_{DS} = 0 V$ ; $T_J = 25 ^\circ C$  | -   | 10  | 100  | nA      |
| $R_{DS(on)}$                  | drain-source on-state resistance | $V_{GS} = 10 V$ ; $I_D = 25 A$ ; $T_J = 25 ^\circ C$ ; <a href="#">Fig. 12</a>                             | -   | 1.3 | 1.5  | mΩ      |
|                               |                                  | $V_{GS} = 10 V$ ; $I_D = 25 A$ ; $T_J = 100 ^\circ C$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>  | -   | -   | 2.1  | mΩ      |
|                               |                                  | $V_{GS} = 4.5 V$ ; $I_D = 25 A$ ; $T_J = 25 ^\circ C$ ; <a href="#">Fig. 12</a>                            | -   | 1.7 | 1.85 | mΩ      |
|                               |                                  | $V_{GS} = 10 V$ ; $I_D = 25 A$ ; $T_J = 175 ^\circ C$ ; <a href="#">Fig. 12</a> ; <a href="#">Fig. 13</a>  | -   | -   | 2.9  | mΩ      |

| Symbol                  | Parameter                         | Conditions   |  | Min | Typ   | Max | Unit |
|-------------------------|-----------------------------------|--|--|-----|-------|-----|------|
| R <sub>G</sub>          | internal gate resistance (AC)     | f = 1 MHz  |  | 0.5 | 1.1   | 2.2 | Ω    |
| Dynamic characteristics |                                   |  |  |     |       |     |      |
| Q <sub>G(tot)</sub>     | total gate charge                 | I <sub>D</sub> = 25 A; V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 10 V; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>     |  | -   | 228   | -   | nC   |
|                         |                                   | I <sub>D</sub> = 25 A; V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 4.5 V; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>    |  | -   | 108   | -   | nC   |
|                         |                                   | I <sub>D</sub> = 0 A; V <sub>DS</sub> = 0 V; V <sub>GS</sub> = 10 V  |  | -   | 210   | -   | nC   |
| Q <sub>GS</sub>         | gate-source charge                | I <sub>D</sub> = 25 A; V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 4.5 V; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>    |  | -   | 31.8  | -   | nC   |
| Q <sub>GS(th)</sub>     | pre-threshold gate-source charge  |  |  | -   | 21.5  | -   | nC   |
| Q <sub>GS(th-pl)</sub>  | post-threshold gate-source charge |  |  | -   | 10.3  | -   | nC   |
| Q <sub>GD</sub>         | gate-drain charge                 |  |  | -   | 33.2  | -   | nC   |
| V <sub>GS(pl)</sub>     | gate-source plateau voltage       | I <sub>D</sub> = 25 A; V <sub>DS</sub> = 15 V; <a href="#">Fig. 14</a> ; <a href="#">Fig. 15</a>                             |  | -   | 2.5   | -   | V    |
| C <sub>iss</sub>        | input capacitance                 | V <sub>DS</sub> = 15 V; V <sub>GS</sub> = 0 V; f = 1 MHz; T <sub>j</sub> = 25 °C; <a href="#">Fig. 16</a>                    |  | -   | 14934 | -   | pF   |
| C <sub>oss</sub>        | output capacitance                |  |  | -   | 2741  | -   | pF   |
| C <sub>rss</sub>        | reverse transfer capacitance      |  |  | -   | 1168  | -   | pF   |
| t <sub>d(on)</sub>      | turn-on delay time                | V <sub>DS</sub> = 15 V; R <sub>L</sub> = 0.6 Ω; V <sub>GS</sub> = 4.5 V; R <sub>G(ext)</sub> = 4.7 Ω; T <sub>j</sub> = 25 °C |  | -   | 100.6 | -   | ns   |
| t <sub>r</sub>          | rise time                         |  |  | -   | 156.1 | -   | ns   |
| t <sub>d(off)</sub>     | turn-off delay time               |  |  | -   | 191.8 | -   | ns   |
| t <sub>f</sub>          | fall time                         |  |  | -   | 99.2  | -   | ns   |
| Source-drain diode      |                                   |  |  |     |       |     |      |
| V <sub>SD</sub>         | source-drain voltage              | I <sub>S</sub> = 25 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 17</a>                                |  | -   | 0.78  | 1.2 | V    |
| t <sub>rr</sub>         | reverse recovery time             | I <sub>S</sub> = 25 A; dI <sub>S</sub> /dt = 100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 15 V                         |  | -   | 62.5  | -   | ns   |
| Q <sub>r</sub>          | recovered charge                  |  |  | -   | 96.8  | -   | nC   |

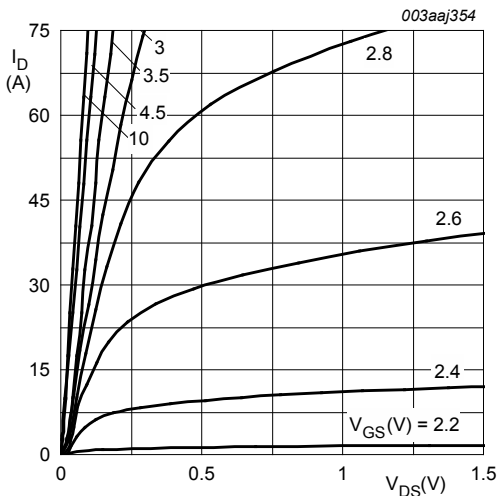


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

$T_j = 25^{\circ}\text{C}$

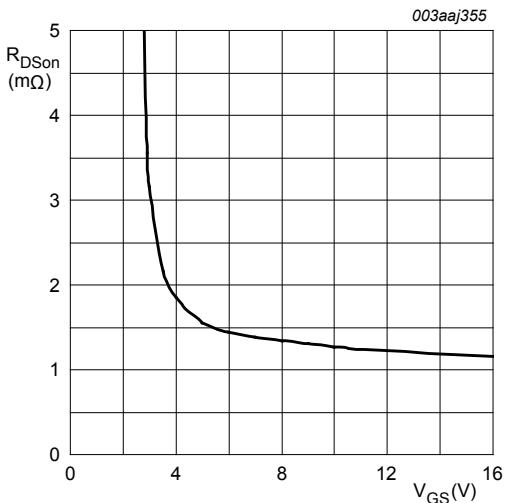


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

$T_j = 25^{\circ}\text{C}; I_D = 25\text{A}$

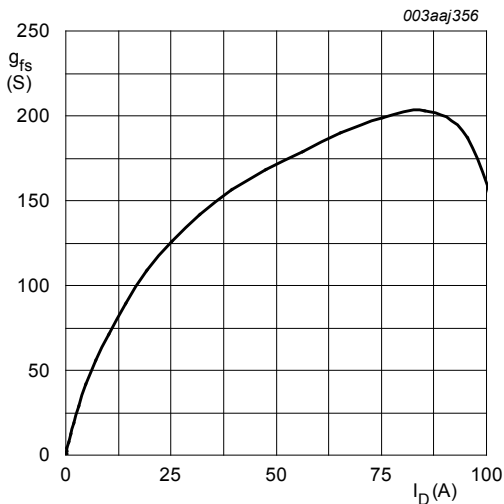


Fig. 8. Forward transconductance as a function of drain current; typical values

$T_j = 25^{\circ}\text{C}; V_{DS} = 10\text{V}$

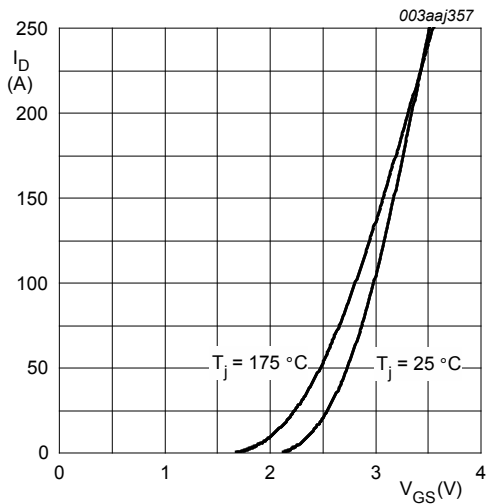


Fig. 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

$V_{DS} = 10\text{V}$

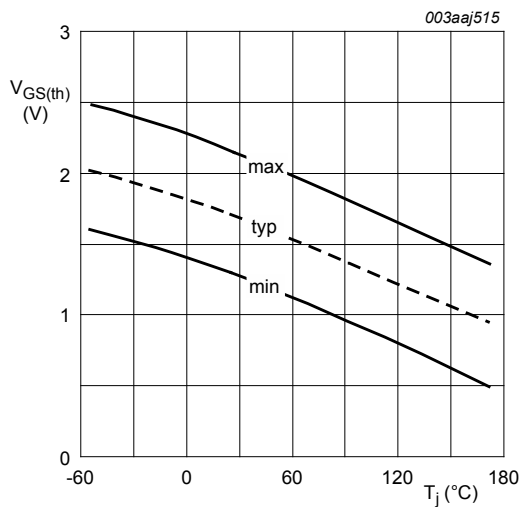


Fig. 10. Gate-source threshold voltage as a function of junction temperature

$$V_{DS} = V_{GS}$$

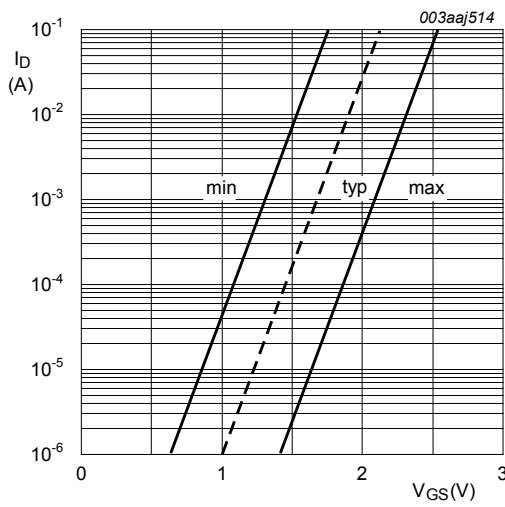


Fig. 11. Sub-threshold drain current as a function of gate-source voltage

$$T_j = 25^{\circ}\text{C}; V_{DS} = 5\text{V}$$

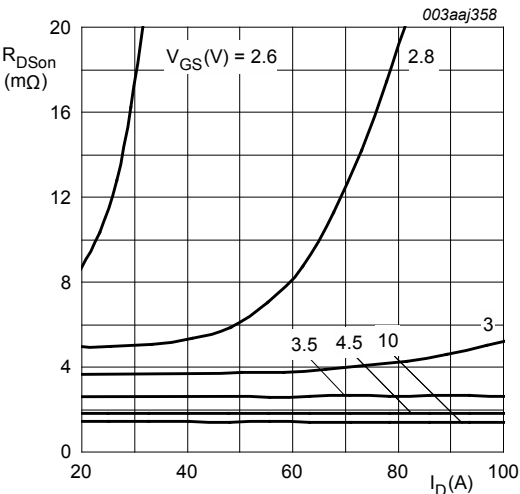


Fig. 12. Drain-source on-state resistance as a function of drain current; typical values

$$T_j = 25^{\circ}\text{C}$$

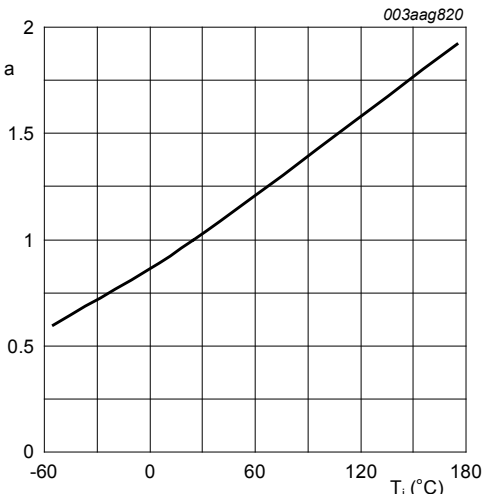


Fig. 13. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^{\circ}\text{C})}}$$



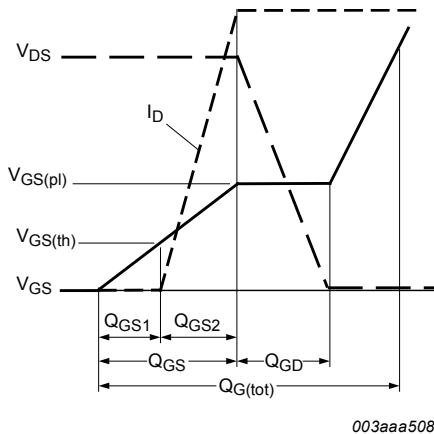


Fig. 14. Gate charge waveform definitions

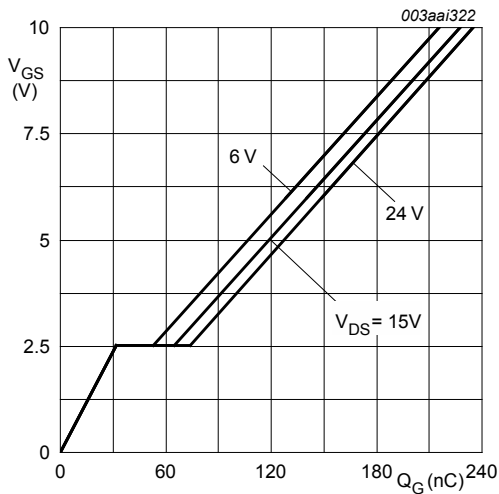


Fig. 15. Gate-source voltage as a function of gate charge; typical values

$T_j = 25^{\circ}C; I_D = 25A$

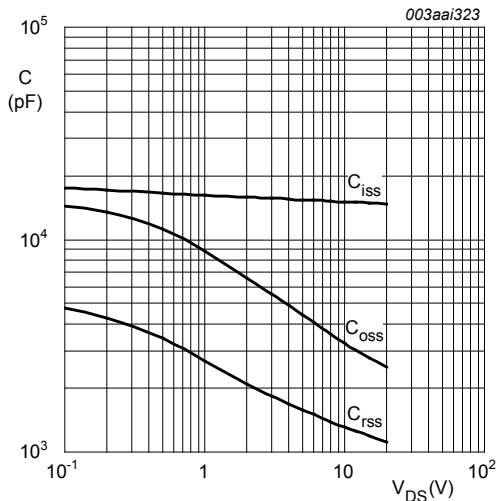


Fig. 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$V_{GS} = 0V; f = 1MHz$

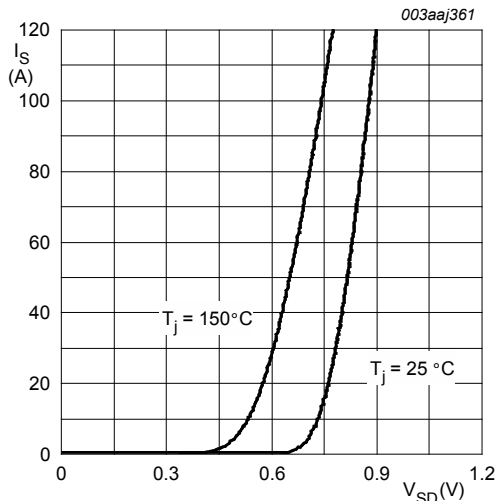


Fig. 17. Source current as a function of source-drain voltage; typical values

$V_{GS} = 0V$

8. Package outline

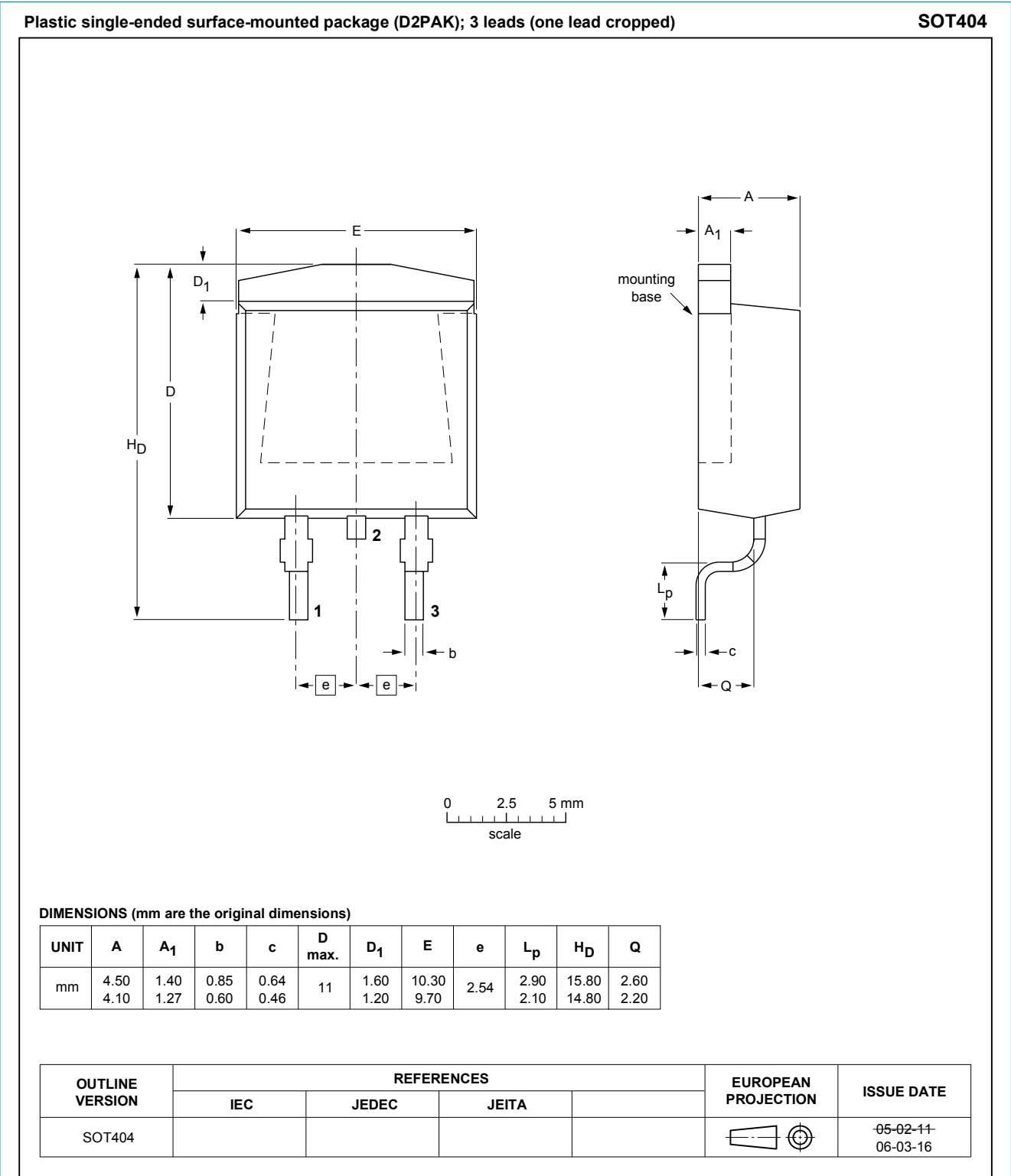


Fig. 18. Package outline D2PAK (SOT404)

## 9. Legal information

### 9.1 Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

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- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

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